

# **MOSFET** - N-Channel, QFET

## **600 V, 23.5 A, 240 m** $\Omega$

## **FQA24N60**

## Description

This N-Channel Enhancement Mode power MOSFET is produced using **onsemi**'s proprietary planar stripe and DMOS technology.

This advanced MOSFET technology has been especially tailored to reduce on-state resistance, and to provide superior switching performance and high avalanche energy strength. These devices are suitable for switched mode power supplies, active power factor correction (PFC), and electronic lamp ballasts.

#### **Features**

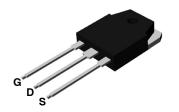
- 23.5 A, 600 V,  $R_{DS(on)} = 240 \text{ m}\Omega$  (Max.) @  $V_{GS} = 10 \text{ V}$ ,  $I_D = 11.8 \text{ A}$
- Low Gate Charge (Typ. 110 nC)
- Low C<sub>rss</sub> (Typ. 56 pF)
- 100% Avalanche Tested
- This Device is Pb-Free

#### **ABSOLUTE MAXIMUM RATINGS**

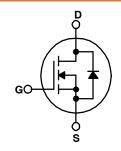
(T<sub>C</sub> = 25°C unless otherwise noted.)

Symbol	Parameter	Value	Unit
V <sub>DSS</sub>	Drain to Source Voltage	600	V
I <sub>D</sub>	Drain Current - Continuous (T <sub>C</sub> = 25°C) - Continuous (T <sub>C</sub> = 100°C)	23.5 14.9	Α
I <sub>DM</sub>	Drain Current - Pulsed (Note 1)	94	Α
V <sub>GSS</sub>	Gate to Source Voltage	±30	V
E <sub>AS</sub>	Single Pulse Avalanche Energy (Note 2)	1300	mJ
I <sub>AR</sub>	Avalanche Current (Note 1)	23.5	Α
E <sub>AR</sub>	Repetitive Avalanche Energy (Note 1)	31	mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)	4.5	V/ns
P <sub>D</sub>	Power Dissipation - (T <sub>C</sub> = 25°C) - Derate Above 25°C	310 2.5	W W/°C
T <sub>J</sub> ,T <sub>STG</sub>	Operating and Storage Temperature Range	-55 to +150	°C
TL	Maximum Lead Temperature for Soldering Purpose, 1/8" from Case for 5 Seconds	300	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.



TO-3P-3L CASE 340BZ



#### **MARKING DIAGRAM**

FQA 24N60 AYWWZZ

FQA24N60 = Specific Device Code
A = Assembly Location
YWW = Date Code (Year & Week)

ZΖ

= Assembly Lot

## **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
FQA24N60	TO-3P-3L (Pb-Free)	450 Units / Tube

## THERMAL CHARACTERISTICS

Symbol	Parameter	Value	Unit
$R_{ heta JC}$	Thermal Resistance, Junction-to-Case, Max	0.4	°C/W
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink, Typ.	0.24	
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient, Max.	40	

## **ELECTRICAL CHARACTERISTICS** (T<sub>C</sub> = 25°C unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit	
Off Charac	Off Characteristics						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> = 0 V, I <sub>D</sub> = 250 μA	600	_	_	V	
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	I <sub>D</sub> = 250 μA, Referenced to 25°C	-	0.6	_	V/°C	
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 600 V, V <sub>GS</sub> = 0 V	-	-	10	μΑ	
		V <sub>DS</sub> = 480 V, T <sub>C</sub> = 125°C	-	-	100	μΑ	
I <sub>GSSF</sub>	Gate-Body Leakage Current, Forward	V <sub>GS</sub> = 30 V, V <sub>DS</sub> = 0 V	-	-	100	nA	
I <sub>GSSR</sub>	Gate-Body Leakage Current, Reverse	$V_{GS} = -30 \text{ V}, V_{DS} = 0 \text{ V}$	-	-	-100	nA	
On Charac	cteristics	•					
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250 \mu A$	3.0	_	5.0	V	
R <sub>DS(on)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 11.8 A	-	0.18	0.24	Ω	
g <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> = 50 V, I <sub>D</sub> = 11.8 A	-	22.5	-	S	
Dynamic C	Characteristics						
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = 25 V, V <sub>GS</sub> = 0 V, f = 1.0 MHz	-	4200	5500	pF	
C <sub>oss</sub>	Output Capacitance		_	550	720	pF	
C <sub>rss</sub>	Reverse Transfer Capacitance		_	56	75	pF	
Switching	Characteristics						
t <sub>d(on)</sub>	Turn-On Delay Time	$V_{DD} = 300 \text{ V}, I_D = 23.5 \text{ A},$	_	90	190	ns	
t <sub>r</sub>	Turn-On Rise Time	$R_G = 25 \Omega \text{ (Note 4)}$	-	270	550	ns	
t <sub>d(off)</sub>	Turn-Off Delay Time		_	200	410	ns	
t <sub>f</sub>	Turn-Off Fall Time		-	170	350	ns	
$Q_g$	Total Gate Charge	$V_{DS} = 480 \text{ V}, I_D = 23.5 \text{ A},$	-	110	145	nC	
Q <sub>gs</sub>	Gate-Source Charge	V <sub>GS</sub> = 10 V (Note 4)	-	25	-	nC	
$Q_{gd}$	Gate-Drain Charge		-	53	-	nC	
Drain-Sou	rce Diode Characteristics and Maximum	Ratings					
I <sub>S</sub>	Maximum Continuous Drain-Source Diode Forward Current		-	-	23.5	Α	
I <sub>SM</sub>	Maximum Pulsed Drain to Source Diode Forward Current		-	-	94	Α	
$V_{SD}$	Drain-Source Diode Forward Voltage	V <sub>GS</sub> = 0 V, I <sub>S</sub> = 23.5 A	-	-	1.4	V	
t <sub>rr</sub>	Reverse Recovery Time	$V_{GS} = 0 \text{ V, } I_{S} = 23.5 \text{ A,}$	-	470	-	ns	
Q <sub>rr</sub>	Reverse Recovery Charge	$dI_F/dt = 100 A/\mu s$	-	6.2	_	μС	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

- 1. Repetitive Rating: Pulse width–limited by maximum junction temperature. 
  2. L = 4.3 mH,  $I_{AS}$  = 23.5 A,  $V_{DD}$  = 50 V,  $R_{G}$  = 25  $\Omega$ , starting  $T_{J}$  = 25°C. 
  3.  $I_{SD} \le 23.5$  A,  $di/dt \le 200$  A/ $\mu$ s,  $V_{DD} \le BV_{DSS}$ , starting  $T_{J}$  = 25°C. 
  4. Essentially independent of operating temperature.

## **TYPICAL CHARACTERISTICS**

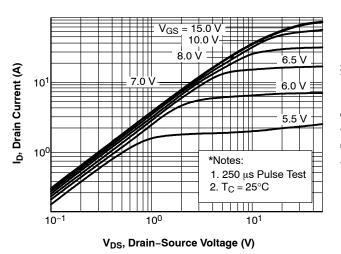


Figure 1. On-Region Characteristics

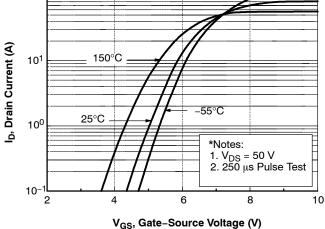


Figure 2. Transfer Characteristics

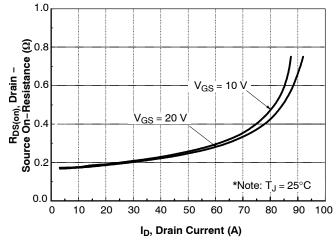


Figure 3. On-Resistance Variation vs Drain Current and Gate Voltage

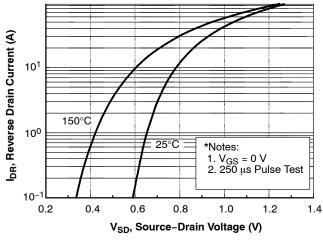


Figure 4. Body Diode Forward Voltage Variation vs Source Current and Temperature

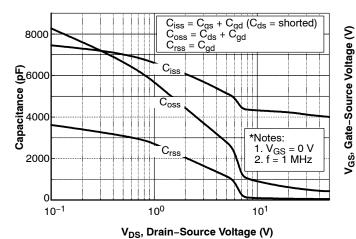


Figure 5. Capacitance Characteristics

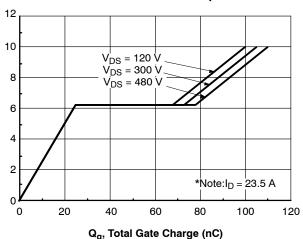


Figure 6. Gate Charge Characteristics

## TYPICAL CHARACTERISTICS (CONTINUED)

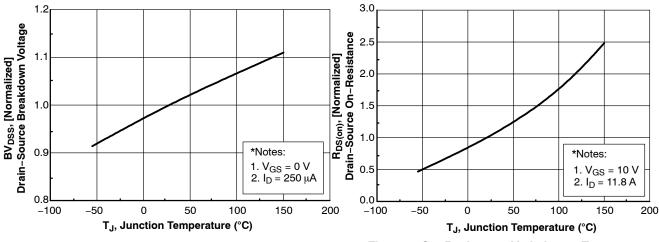


Figure 7. Breakdown Voltage Variation vs Temperature

Figure 8. On-Resistance Variation vs Temperature

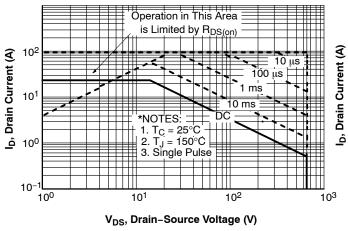
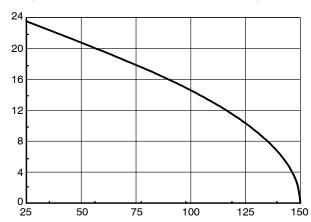
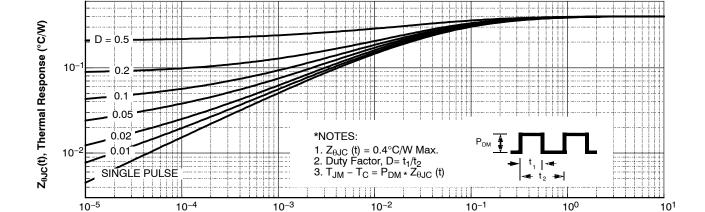


Figure 9. Maximum Safe Operating Area



T<sub>C</sub>, Case Temperature (°C)
Figure 10. Maximum Drain Current
vs. Case Temperature



t<sub>1</sub>, Rectangular Pulse Duration (s)

Figure 11. Transient Thermal Response Curve

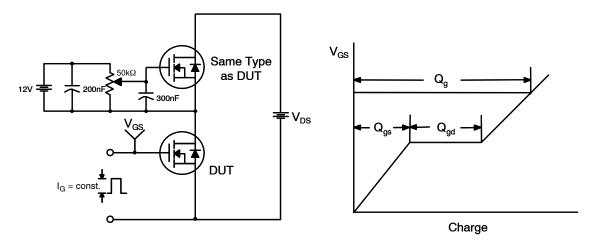


Figure 12. Gate Charge Test Circuit & Waveform

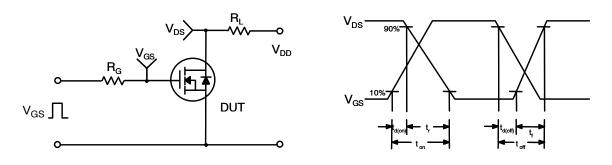


Figure 13. Resistive Switching Test Circuit & Waveforms

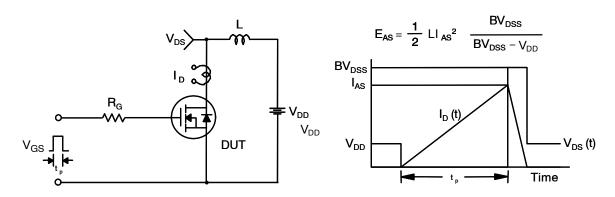
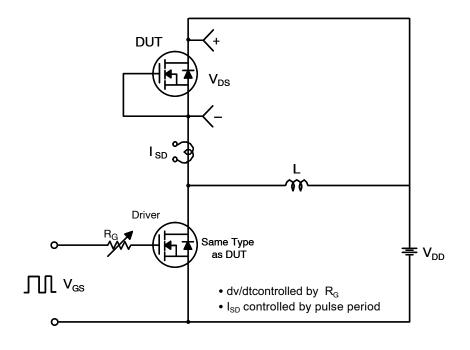


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms



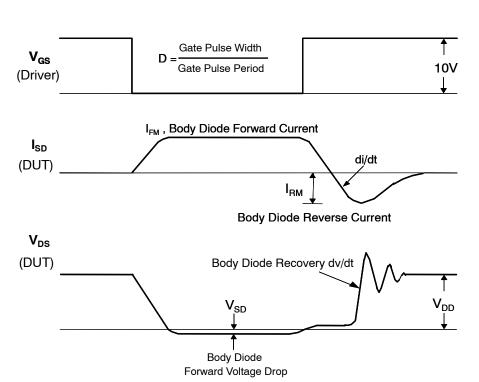
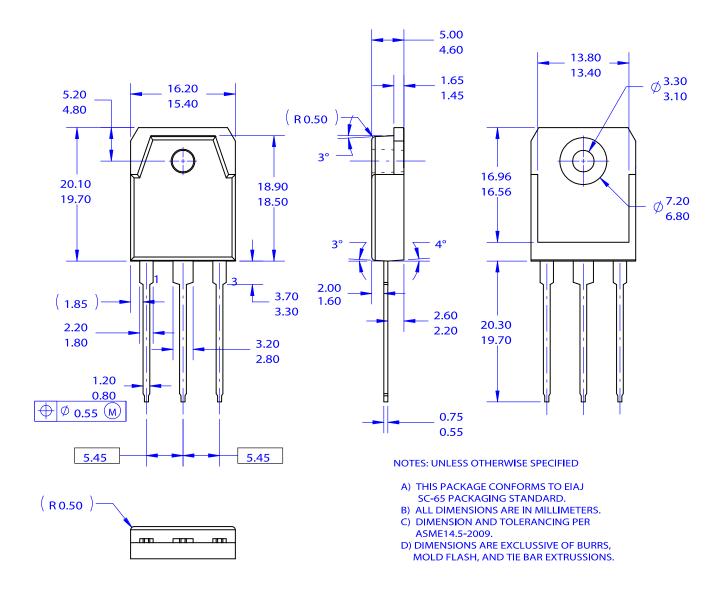


Figure 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms



## TO-3P-3LD / EIAJ SC-65, ISOLATED CASE 340BZ ISSUE O

**DATE 31 OCT 2016** 



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